Undated Search 762587 11 December 2003 L Number Hits Search Text DB (US-6309524-\$ or US-5932077-\$ or US-5522975-\$ USPAT. 2003/12/11 10:53 2 US-PGPUB: or US-6197181-\$ or US-5415890-\$ or US-5849171-\$ or US-4163705-\$ or US-5433840-\$ or FPO: JPO: US-4430173-\$ or US-6294059-\$ or US-5437777-\$ DERWENT or US-4666735-\$ or US-6140234-\$ or US-6117784-\$ or US-4749449-\$ or US-4490220-\$ or US-4303443-\$ or US-6458251-\$ or US-6143155-\$ or US-5462670-\$ or US-5230782-\$ or US-4956097-\$ or US-4299671-\$ or US-3833486-\$).did. or (US-20020000372-\$ or US-20020008034-\$ or US-20020005359-\$).did. or (US-5342806-\$ or GB-2285174-\$).did. or (JP-05311496-\$ or JP-07193214-\$ or JP-56158424-\$ or JP-56161221-\$ or JP-03146698-\$ or JP-63026400-\$).did. or (GB-2285174-\$ or JP-56158424-\$ or JP-63026400-\$ or GB-1222969-\$).did. 2003/12/11 USPAT; 5 6080291.pn. US-PGPUB: 09:42 EPO: JPO: DERWENT USPAT: 2003/12/11 10:33 6 0 762582.apn. US-PGPUB: FPO: JPO: DERWENT ((US-6309524-\$ or US-5932077-\$ or USPAT: 2003/12/11 10:57 7 US-5522975-\$ or US-6197181-\$ or US-5415890-\$ US-PGPUB: or US-5849171-\$ or US-4163705-\$ or EPO: JPO: DERWENT US-5433840-\$ or US-4430173-\$ or US-6294059-\$ or US-5437777-\$ or US-4666735-\$ or US-6140234-\$ or US-6117784-\$ or US-4749449-\$ or US-4490220-\$ or US-4303443-\$ or US-6458251-\$ or US-6143155-\$ or US-5462670-\$ or US-5230782-\$ or US-4956097-\$ or US-4299671-\$ or US-3833486-\$).did. or (US-20020000372-\$ or US-20020008034-\$ or US-20020005359-\$).did. or (US-5342806-\$ or GB-2285174-\$).did. or (JP-05311496-\$ or JP-07193214-\$ or JP-56158424-\$ or JP-56161221-\$ or JP-03146698-\$ or JP-63026400-\$).did. or (GB-2285174-\$ or JP-56158424-\$ or JP-63026400-\$ or GB-1222969-\$).did.) and (activat\$) 2003/12/11 10:57 R 108 205/183.ccls. and (activat\$ or palladium) USPAT: US-PGPUB: EPO; JPO; DERWENT 57 (205/183.ccls. and (activat\$ or palladium)) and USPAT: 2003/12/11 11:06 9 electroless US-PGPUB: EPO: JPO:

DERWENT

_				
10	207	205/\$.ccls. and (electroless same ((palladium or pd!)	USPAT;	2003/12/11 11:08
		with (tin or Sn!)))	U5-PGPUB;	
			EPO; JPO;	
1			DERWENT	
11	98	205/\$.ccls. and (electroless same activat\$7 same	USPAT;	2003/12/11 11:16
		((palladium or pd!) with (tin or Sn!)))	US-PGPUB;	
	İ		EPO; JPO;	
1			DERWENT	
12	1	205/\$.ccls. and (electroless same activat\$7 same	USPAT;	2003/12/11 11:25
		((palladium or pd!) same (tin or Sn!)) same	US-PGPUB;	
	Ì	(semiconductor or microelectronic))	EPO; JPO;	
1			DERWENT	
13	80	204/\$.ccls. and ((semiconductor or microelectronic)	USPAT;	2003/12/11 11:28
		and (shield\$3 adj plate))	US-PGPUB;	}
	i		EPO; JPO;	
			DERWENT	
14	5	(204/\$.ccls. and ((semiconductor or microelectronic)	USPAT;	2003/12/11 11:26
		and (shield\$3 adj plate))) and (electroplat\$6)	US-PGPUB;	
			EPO; JPO;	}
			DERWENT	
15	0	204/\$.ccls. and ((semiconductor or microelectronic)	USPAT;	2003/12/11 11:28
		and (thie\$3 adj plate))	US-PGPUB;	l i
ļ			EPO; JPO;	
			DERWENT	
16	0	204/\$.ccls. and ((semiconductor or microelectronic)	USPAT;	2003/12/11 11:29
		and (thie\$5 adj plate))	US-PGPUB;	}
	İ		EPO; JPO;	
1			DERWENT	
17	6	204/\$.ccls. and ((semiconductor or microelectronic)	USPAT;	2003/12/11 11:54
	ļ	and (thie\$5 adj electrode))	US-PGPUB;	
			EPO; JPO;	
100			DERWENT	
18	128	204/\$.ccls. and ((semiconductor or microelectronic)	USPAT;	2003/12/11 11:55
		and ((clean\$6 or rins\$6) with (spin\$6 or spun)))	US-PGPUB;	
			EPO; JPO;	
10	107	004/4 1 1/4 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	DERWENT	
19	107	204/\$.ccls. and ((semiconductor or microelectronic)	USPAT;	2003/12/11 11:56
		and ((clean\$6 or rins\$6) with (spin\$6 or spun) with	US-PGPUB;	
		(dry\$5 or dried)))	EPO; JPO;	
20	63	204/4	DERWENT	
20	63	204/\$.ccls. and ((semiconductor or microelectronic)	USPAT;	2003/12/11 11:57
		and ((clean\$6 or rins\$6) with (spin\$6 or spun) with	US-PGPUB;	
		(dry\$5 or dried))) and electroplat\$5	EPO; JPO;	
		742502	DERWENT	0000 40 44 40 55
_	0	762582.apn.	USPAT;	2003/12/11 10:33
			US-PGPUB;	
			EPO; JPO;	
_	9	(("5116/120") on ("2716/162") ("2020062")) DV	DERWENT	2002/04/20
-	9	(("5116430") or ("3716462") or ("3930963")).PN.	USPAT;	2003/04/29
			US-PGPUB;	13:53
		i	EPO; JPO;	
			DERWENT	

		T. #44.0404 + 44	T-1	T = 2 = 2 = 2
-	1	jp-51149131-\$.did.	USPAT;	2003/04/29
			US-PGPUB;	12:13
			EPO; JPO;	
			DERWENT	
-	2	4163705.pn.	USPAT;	2003/04/29
		, ·	US-PGPUB;	12:13
			EPO; JPO;	
			DERWENT	
_	7	(("5849171") or ("4430173") or ("5433840")).PN.	USPAT;	2003/04/30
		((55 1) 27 1 7 51 (1 10027 5) 61 (5 100010))14.	US-PGPUB;	09:43
1				09.43
			EPO; JPO;	
	2/57	204 (100 212 222 242 272 275 1	DERWENT	0000101100
-	2657	204/198,212,232,242,273,275.1.ccls.	USPAT;	2003/04/29
			US-PGPUB;	13:55
			EPO; JPO;	
			DERWENT	
-	773	204/224r.ccls.	USPAT;	2003/04/29
1	1		US-PGPUB;	13:55
	1		EPO; JPO;	
	1		DERWENT	
-	3270	204/198,212,232,242,273,275.1.ccls. 204/224r.ccls.	USPAT;	2003/04/29
			US-PGPUB;	13:55
			EPO; JPO;	
			DERWENT	
_	35	(204/198,212,232,242,273,275.1.ccls.	USPAT;	2003/04/29
	00	204/224r.ccls.) and electroless and (electrolytic or	US-PGPUB;	14:04
		electroplating) and robot	EPO; JPO;	17.04
		electropianing) and robot	DERWENT	
	58753	204/\$.ccls.		2002/04/20
-	36733	204/\$.ccis.	USPAT;	2003/04/29
			US-PGPUB;	14:04
			EPO; JPO;	
ļ		CONTRACT CON	DERWENT	
-	55	204/\$.ccls. and electroless and (electrolytic or	USPAT;	2003/04/29
		electroplating) and robot	US-PGPUB;	14:04
			EPO; JPO;	
			DERWENT	
-	20	(204/\$.ccls. and electroless and (electrolytic or	USPAT;	2003/04/29
		electroplating) and robot) not	U5-PGPUB;	14:14
		((204/198,212,232,242,273,275.1.ccls.	EPO; JPO;	
		204/224r.ccls.) and electroless and (electrolytic or	DERWENT	
		electroplating) and robot)		
-	2	6080291.pn.	USPAT;	2003/04/29
		'	US-PGPUB:	14:07
			EPO; JPO;	
į i			DERWENT	
_	813	204/\$.ccls. and (robot or robotic)	USPAT;	2003/04/29
	013	as it places, and from the following	US-PGPUB;	14:14
]				14.14
			EPO; JPO;	
i	70	(201/4	DERWENT	0000 (04 (00
-	78	(204/\$.ccls. and (robot or robotic)) and electroless	USPAT;	2003/04/29
			US-PGPUB;	14:15
			EPO; JPO;	
L			DERWENT	

Г	81	204/\$ and alcotrologo and (unbot an unbotic an	LICDAT	2002/04/20
-	01	204/\$.ccls. and electroless and (robot or robotic or	USPAT;	2003/04/29
		(transfer adj unit) or (transfer adj device) or	US-PGPUB;	14:16
İ		(transfer adj arm))	EPO; JPO;	
	24	(201/4 -	DERWENT	0000 45 4 45
-	26	(204/\$.ccls. and electroless and (robot or robotic or	USPAT;	2003/04/29
		(transfer adj unit) or (transfer adj device) or	US-PGPUB;	14:17
		(transfer adj arm))) not (204/\$.ccls. and electroless	EPO; JPO;	
		and (electrolytic or electroplating) and robot) not	DERWENT	
		((204/\$.ccls. and electroless and (electrolytic or		
		electroplating) and robot) not		
		((204/198,212,232,242,273,275.1.ccls.		
		204/224r.ccls.) and electroless and (electrolytic or		
		electroplating) and robot))		
-	26	(204/\$.ccls. and electroless and (robot or robotic or	USPAT;	2003/04/29
		(transfer adj unit) or (transfer adj device) or	US-PGPUB;	14:33
		(transfer adj arm))) not (204/\$.ccls. and electroless	EPO; JPO;	
		and (electrolytic or electroplating) and robot) not	DERWENT	
		((204/198,212,232,242,273,275.1.ccls.		
		204/224r.ccls.) and electroless and (electrolytic or		
		electroplating) and robot)		
_	2	6197181.pn.	USPAT;	2003/04/29
			US-PGPUB;	14:21
			EPO; JPO;	
			DERWENT	
-	2	jp-56158424-\$.did.	USPAT;	2003/04/29
	-		US-PGPUB;	14:34
			EPO; JPO;	
	l , i		DERWENT	
-	1	1982-04830E.NRAN.	DERWENT	2003/04/29
		. 0504404 6 114		14:33
i -	2	jp-05311496-\$.did.	USPAT;	2003/04/29
			US-PGPUB;	14:35
			EPO; JPO;	
	2	to 07103314 # Jt J	DERWENT	0000 (04 (00
-		jp-07193214-\$.did.	USPAT;	2003/04/29
i			US-PGPUB;	14:37
			EPO; JPO;	
_	1	1995-217803.NRAN,	DERWENT	2003/04/20
		1775 L17005.INK/IN,	DERWENT	2003/04/29 14:37
i _	2	.jp-02000341-\$.did.	USPAT;	2003/04/29
	<u>"</u> ا	JP 0200071 P.did.	US-PGPUB;	14:39
			EPO; JPO;	17.37
			DERWENT	
_	1 1	1990-047945.NRAN.	DERWENT	2003/04/29
		and a second sec	DERVICINI	14:39
_	2	jp-56161221-\$.did.	USPAT;	2003/04/29
		All agreement district.	US-PGPUB;	14:42
			EPO; JPO;	- "
			DERWENT	
_	1	.jp-51149131-\$.did.	USPAT;	2003/04/29
		Ur	US-PGPUB;	14:43
			EPO; JPO;	0
			DERWENT	
				L

		4074 754004410	S EDVACE UT	2000 104 100
-	1	1976-75692X.NRAN.	DERWENT	2003/04/29
	2	5 02144400 ft did	USPAT;	14:42
-	2	jp-03146698-\$.did.	US-PGPUB;	2003/04/29 14:44
			EPO; JPO;	14:44
			DERWENT	
	2	jp-05098500-\$.did.	USPAT;	2003/05/01 10:11
_	_	3p-05076500-φ.αια.	US-PGPUB;	2003/05/01 10:11
			EPO; JPO;	
			DERWENT	
_	2	jp-62235499-\$.did.	USPAT;	2003/04/29
	_	JP 02233 177 \$.c.id.	US-PGPUB;	14:46
			EPO; JPO;	11.10
			DERWENT	
_	2	jp-63026400-\$.did.	USPAT;	2003/04/29
	"	- 3ρ σσσμο του φιατα.	US-PGPUB;	14:50
			EPO; JPO;	
			DERWENT	
-	1	1997wo-??22733.ap,prai.	USPAT;	2003/04/29
		,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	US-PGPUB;	14:51
			EPO; JPO;	
			DERWENT	
-	0	wo-22733-\$.did.	USPAT;	2003/04/29
			U5-PGPUB;	14:52
			EPO; JPO;	
			DERWENT	
-	0	wo-00022733-\$.did.	USPAT;	2003/04/29
			US-PGPUB;	14:52
			EPO; JPO;	
			DERWENT	
-	0	wo-97022733-\$.did.	USPAT;	2003/04/29
			US-PGPUB;	14:52
			EPO; JPO;	
		2011	DERWENT	0000 104 100
-	58753	204/\$.ccls.	USPAT;	2003/04/29 15:10
			US-PGPUB; EPO; JPO;	15:10
			DERWENT	
_	708	204/\$.ccls. and (electroless and (electrolytic or	USPAT;	2003/04/29
	, 08	electroplating or electroplate))	US-PGPUB;	15:11
		Section of the sectio	EPO; JPO;	
1			DERWENT	
-	82	(204/\$.ccls. and (electroless and (electrolytic or	USPAT;	2003/04/29
		electroplating or electroplate))) and (robot or robotic	US-PGPUB;	15:12
		or ((transfer or conveyance or conveyor) adj (means!	EPO; JPO;	
		or unit or device or system or arm)))	DERWENT	
-	160054	205/\$.ccls. or 427/\$.ccls.	USPAT;	2003/04/29
			US-PGPUB;	15:47
			EPO; JPO;	
			DERWENT	
-	14963	(205/\$.ccls. or 427/\$.ccls.) and (semiconductor or	USPAT;	2003/04/29
		wafer)	US-PGPUB;	15:48
			EPO; JPO;	
L	L	<u></u>	DERWENT	

-	759	((205/\$.ccls. or 427/\$.ccls.) and (semiconductor or	USPAT;	2003/04/29
		wafer)) and electroless and (electroplating or	US-PGPUB;	15:49
		electroplated or electroplate or electrolytic or	EPO; JPO;	İ
	[electrochemically)	DERWENT	
-	54	((205/\$.ccls. or 427/\$.ccls.) and (semiconductor or	USPAT;	2003/04/29
		wafer)) and (electroless near2 (tank or bath)) and	US-PGPUB;	15:49
		((electroplating or electroplated or electroplate or	EPO; JPO;	
		electrolytic or electrochemically) near2 (tank or	DERWENT	
		bath))		
-	60	((205/\$.ccls. or 427/\$.ccls.) and (semiconductor or	USPAT;	2003/04/29
		wafer)) and (electroless near2 (tank or bath or	US-PGPUB;	15:54
		chamber)) and ((electroplating or electroplated or	EPO; JPO;	
		electroplate or electrolytic or electrochemically)	DERWENT	
		near2 (tank or bath or chamber))		
-	7	(((205/\$.ccls. or 427/\$.ccls.) and (semiconductor or	USPAT;	2003/04/29
		wafer)) and (electroless near2 (tank or bath or	US-PGPUB;	15:51
		chamber)) and ((electroplating or electroplated or	EPO; JPO;	
		electroplate or electrolytic or electrochemically)	DERWENT	
		near2 (tank or bath or chamber))) and (robot or		
		robotic or ((transfer or conveyor or conveyance) near		
		(arm or unit or device or means!)))		
-	29	(((205/\$.ccls. or 427/\$.ccls.) and (semiconductor or	USPAT;	2003/04/29
		wafer)) and (electroless near2 (tank or bath or	US-PGPUB;	15:55
		chamber)) and ((electroplating or electroplated or	EPO; JPO;	
		electroplate or electrolytic or electrochemically)	DERWENT	
		near2 (tank or bath or chamber))) and ((copper adj		
		sulfate) or "Cuso.sub.4")		
-	8	(("5500315") or ("5310580") or ("5389496") or	USPAT;	2003/04/30
		("5139818")).PN.	US-PGPUB;	08:52
			EPO; JPO;	
			DERWENT	
-	0	electroless and ((copper adj sulfate) or "cuso.sub.4")	USPAT;	2003/04/30
		and ((chlorine or chloride) adj ions) and (sufuric adj	US-PGPUB;	08:54
		acid)	EPO; JPO;	
			DERWENT	
-	1896	electroless and ((copper adj sulfate) or "cuso.sub.4")	USPAT;	2003/04/30
			US-PGPUB;	08:54
			EPO; JPO;	
			DERWENT	
-	1019	(electroless and ((copper adj sulfate) or	USPAT;	2003/04/30
		"cuso.sub.4")) and (sulfuric adj acid)	US-PGPUB;	08:54
			EPO; JPO;	
			DERWENT	
-	220	((electroless and ((copper adj sulfate) or	USPAT;	2003/04/30
		"cuso.sub.4")) and (sulfuric adj acid)) and	US-PGPUB;	08:55
		(((polyethylene or polypropylene) adj glycol) or pegl or	EPO; JPO;	
l		ppg!)	DERWENT	
-	52	(((electroless and ((copper adj sulfate) or	USPAT;	2003/04/30
		"cuso.sub.4")) and (sulfuric adj acid)) and	US-PGPUB;	08:55
		(((polyethylene or polypropylene) adj glycol) or pegl or	EPO; JPO;	
		ppg!)) and sulfur and nitrogen	DERWENT	

	F.4	////	LICDAT	0000 10 1 10 0
-	51	((((electroless and ((copper adj sulfate) or	USPAT;	2003/04/30
i		"cuso.sub.4")) and (sulfuric adj acid)) and	US-PGPUB;	09:06
		(((polyethylene or polypropylene) adj glycol) or peg! or	EPO; JPO;	
		ppg!)) and sulfur and nitrogen) and (chlorine or	DERWENT	
		chloride)	lies . T	2002 (04 (20
-	0	uk-1222969-\$.did.	USPAT;	2003/04/30
			US-PGPUB;	09:07
İ	ļ		EPO; JPO;	
		1 1222042 4 111	DERWENT	2000/04/00
-	1	gb-1222969-\$.did.	USPAT;	2003/04/30
			US-PGPUB;	09:11
			EPO; JPO;	
	59	(204/4 1, 205/4 1,) 11 111 1/	DERWENT	2002 (04 (20
-	59	(204/\$.ccls. or 205/\$.ccls.) and bubble and (pressure	USPAT;	2003/04/30
		near (module or modulation or modulating or pulse or	US-PGPUB;	10:01
		pulsating or pulsed or pulsing or pulsated or varied or	EPO; JPO;	
	8	variable or cyclical))	DERWENT	2002 (04 (22
_	8	(204/\$.ccls. or 205/\$.ccls.) and (bubble with	USPAT;	2003/04/30
		(pressure near (module or modulation or modulating	US-PGPUB;	10:09
		or pulse or pulsating or pulsed or pulsing or pulsated	EPO; JPO;	
	111	or varied or variable or cyclical))) (204/\$.ccls. or 205/\$.ccls.) and ((bubble or gas)	DERWENT	2002/04/20
-	111		USPAT;	2003/04/30
		same (pressure near (module or modulation or	US-PGPUB;	10:20
		modulating or pulse or pulsating or pulsed or pulsing	EPO; JPO;	
	102	or pulsated or varied or variable or cyclical)))	DERWENT	2002/04/20
-	102	(204/\$.ccls. or 205/\$.ccls.) and ((bubble or gas)	USPAT;	2003/04/30
		same (pressure near (modulate or modulation or	US-PGPUB;	13:38
		modulating or pulse or pulsating or pulsed or pulsing or pulsated or varied or variable or cyclical)))	EPO; JPO;	
	21529	(204/\$.ccls. or 205/\$.ccls.) and (semiconductor or	DERWENT	2002/04/20
-	21329	wafer or microelectronic or (integrated adj circuit)	USPAT; US-PGPUB;	2003/04/30 10:19
		or (circuit board))	EPO; JPO;	10:19
		or (circuit bourd))	DERWENT	
	2051	((204/\$.ccls. or 205/\$.ccls.) and (semiconductor or	USPAT;	2003/04/30
	2001	wafer or microelectronic or (integrated adj circuit)	US-PGPUB;	10:19
		or (circuit board))) and bubble	EPO; JPO;	10.17
i		or (or our, board))) and bubble	DERWENT	
_	241	((204/\$.ccls. or 205/\$.ccls.) and (semiconductor or	USPAT;	2003/04/30
	"'"	wafer or microelectronic or (integrated adj circuit)	US-PGPUB:	10:20
		or (circuit board))) and (bubble with pressure)	EPO; JPO;	10.00
		The contract of the contract o	DERWENT	
_	69	((204/\$.ccls. or 205/\$.ccls.) and (semiconductor or	USPAT;	2003/04/30
j	-	wafer or microelectronic or (integrated adj circuit)	US-PGPUB;	10:21
	ĺ	or (circuit board))) and ((bubble or gas) same	EPO; JPO;	
		(pressure near (modulate or modulation or modulating	DERWENT	
		or pulse or pulsating or pulsed or pulsing or pulsated		
		or varied or variable or cyclical)))		
_	2	5865894.pn.	USPAT;	2003/04/30
	-	•	US-PGPUB;	13:41
	į		EPO: JPO:	
			DERWENT	
			DERWENT	

_	83136	204/\$.ccls. or 205/\$.ccls.	USPAT;	2003/04/30
			US-PGPUB:	13:41
			EPO; JPO;	
			DERWENT	
_	18	(204/\$.ccls. or 205/\$.ccls.) and (semiconductor) and	USPAT;	2003/04/30
		(bubbles with (sonic or ultrasonic or megasonic))	US-PGPUB;	13:45
		` ` ` ` "	EPO, JPO;	
			DERWENT	
-	2	((204/\$.ccls. or 205/\$.ccls.) and (semiconductor) and	USPAT;	2003/04/30
		(bubbles with (sonic or ultrasonic or megasonic))) and	US-PGPUB;	13:45
		(hermetically or sealed)	EPO; JPO;	
		•	DERWENT	
_	1933	(204/198,212,232,242,273,275.1.ccls. 204/224r.ccls.	USPAT;	2003/04/30
		205/88,98,122,123,125,148,157,183,184,187,261,291.cd	ISUS-PGPUB;	14:07
		427/96,98,443.1.ccls.) and semiconductor	EPO; JPO;	
			DERWENT	
-	506	((204/198,212,232,242,273,275.1.ccls.	USPAT;	2003/04/30
		204/224r.ccls.	US-PGPUB;	14:07
	:	205/88,98,122,123,125,148,157,183,184,187,261,291.cd		
		427/96,98,443.1.ccls.) and semiconductor) and	DERWENT	
-	135	(((20)4d)(1985,212,232,242,273,275.1.ccls.	USPAT;	2003/04/30
		204/224r.ccls.	US-PGPUB;	14:08
		205/88,98,122,123,125,148,157,183,184,187,261,291.cd		
		427/96,98,443.1.ccls.) and semiconductor) and	DERWENT	
		electroless) and ((copper adj (sulfate or sulphate))		
-	61	6(((2014/1916),2117),232,242,273,275.1.ccls.	USPAT;	2003/04/30
		204/224r.ccls.	US-PGPUB;	14:11
		205/88,98,122,123,125,148,157,183,184,187,261,291.cd		
		427/96,98,443.1.ccls.) and semiconductor) and	DERWENT	
	İ	electroless) and ((copper adj (sulfate or sulphate))		
-	18	(f(((2046)936,2173)2332, (MA)27737275 thin in internal)	USPAT;	2003/04/30
		204/224r.ccls.	US-PGPUB;	14:12
		205/88,98,122,123,125,148,157,183,184,187,261,291.cd		
		427/96,98,443.1.ccls.) and semiconductor) and	DERWENT	
İ		electroless) and ((copper adj (sulfate or sulphate))		0000/04/00
-	2	((((2046)9.18,217)23,12,742,2773,2755.dticler trasnfer)	USPAT;	2003/04/30
		204/224r.ccis.	US-PGPUB;	14:12
		205/88,98,122,123,125,148,157,183,184,187,261,291.cd		
		427/96,98,443.1.ccls.) and semiconductor) and	DERWENT	
L		electroless) and ((copper adj (sulfate or sulphate))		

or "cuso.sub.4")) and hermetically

-	31	(US-4163705-\$ or US-5849171-\$ or US-4430173-\$	USPAT;	2003/04/30
	J.	or US-5433840-\$ or US-6294059-\$ or	US-PGPUB;	14:56
1		US-5437777-\$ or US-6309524-\$ or US-5932077-\$		14:56
			EPO; JPO;	
		or US-5522975-\$ or US-5415890-\$ or	DERWENT	
		US-6197181-\$ or US-4666735-\$ or US-6140234-\$		
		or US-6117784-\$ or US-4749449-\$ or	i	
		US-4490220-\$ or US-4303443-\$ or		
		US-6458251-\$).did. or (US-20020000372-\$ or		
		US-20020008034-\$ or US-20020005359-\$).did. or		
		(GB-2285174-\$ or US-5342806-\$).did. or		
		(JP-56158424-\$ or JP-05311496-\$ or		
		JP-07193214-\$ or JP-56161221-\$ or JP-03146698-\$		
		or JP-63026400-\$).did. or (JP-56158424-\$ or		İ
		GB-2285174-\$ or JP-63026400-\$ or		
		GB-1222969-\$).did.		
_	11	((US-4163705-\$ or US-5849171-\$ or US-4430173-\$	USPAT;	2003/04/30
		or US-5433840-\$ or US-6294059-\$ or	US-PGPUB;	14:57
		US-5437777-\$ or US-6309524-\$ or US-5932077-\$	EPO: JPO:	14.07
		or US-5522975-\$ or US-5415890-\$ or	DERWENT	
		US-6197181-\$ or US-4666735-\$ or US-6140234-\$	DEKWENT	
		or US-6117784-\$ or US-4749449-\$ or		
		US-4490220-\$ or US-4303443-\$ or		
		US-6458251-\$).did. or (US-20020000372-\$ or		
	İ	US-20020008034-\$ or US-20020005359-\$).did. or		
		(GB-2285174-\$ or US-5342806-\$).did. or		
		(JP-56158424-\$ or JP-05311496-\$ or		
		JP-07193214-\$ or JP-56161221-\$ or JP-03146698-\$		
		or JP-63026400-\$).did. or (JP-56158424-\$ or		
		GB-2285174-\$ or JP-63026400-\$ or		
		GB-1222969-\$).did.) and (waste or disposal or		
		dispose or disposed)		
-	4	((US-4163705-\$ or US-5849171-\$ or US-4430173-\$	USPAT;	2003/04/30
		or US-5433840-\$ or US-6294059-\$ or	US-PGPUB;	14:57
		US-5437777-\$ or US-6309524-\$ or US-5932077-\$	EPO; JPO;	
		or US-5522975-\$ or US-5415890-\$ or	DERWENT	
		US-6197181-\$ or US-4666735-\$ or US-6140234-\$	SERVEIN	
		or US-6117784-\$ or US-4749449-\$ or		
		US-4490220-\$ or US-4303443-\$ or		
		US-6458251-\$).did. or (US-20020000372-\$ or	1	1
		US-20020008034-\$ or US-20020005359-\$).did. or		İ
		(GB-2285174-\$ or US-5342806-\$).did. or		
		(JP-56158424-\$ or JP-05311496-\$ or		
		JP-07193214-\$ or JP-56161221-\$ or JP-03146698-\$		
		or JP-63026400-\$).did. or (JP-56158424-\$ or		
		GB-2285174-\$ or JP-63026400-\$ or		
		GB-1222969-\$).did.) and (waste or disposal)		
-	10914	204/198,212,232,242,273,275.1.ccls. 204/224r.ccls.	USPAT;	2003/04/30
i		205/88,98,122,123,125,148,157,183,184,187,261,291.cc		14:59
		427/96,98,443.1.ccls.	EPO; JPO;	''
		V V	DERWENT	
_	294	(204/198,212,232,242,273,275.1.ccls. 204/224r.ccls.	USPAT;	2003/04/30
	L) T	205/88,98,122,123,125,148,157,183,184,187,261,291.cc		15:00
				13.00
		427/96,98,443.1.ccls.) and electroless and (waste or	EPO; JPO;	
	L	disposal)	DERWENT	Li

	209	(204/198,212,232,242,273,275.1.ccls. 204/224r.ccls.	USPAT;	2003/04/30
		205/88,98,122,123,125,148,157,183,184,187,261,291.cd		15:00
		427/96,98,443.1.ccls.) and (electroless with (solution	EPO; JPO;	
		or bath)) and (waste or disposal)	DERWENT	
_	76	(204/198,212,232,242,273,275.1.ccls. 204/224r.ccls.	USPAT;	2003/04/30
		205/88,98,122,123,125,148,157,183,184,187,261,291.cd		15:00
		427/96,98,443.1.ccls.) and ((electroless with	EPO; JPO;	
		(solution or bath)) same (waste or disposal))	DERWENT	
_	38	(204/198,212,232,242,273,275.1.ccls. 204/224r.ccls.	USPAT;	2003/04/30
		205/88,98,122,123,125,148,157,183,184,187,261,291.cc		15:02
		427/96,98,443.1.ccls.) and ((electroless with	EPO; JPO;	10.00
		(solution or bath)) with (waste or disposal))	DERWENT	
_	45	(204/198,212,232,242,273,275.1.ccls. 204/224r.ccls.	USPAT;	2003/04/30
		205/88,98,122,123,125,148,157,183,184,187,261,291.cc		15:02
		427/96,98,443.1.ccls.) and ((electroless near2	EPO; JPO;	
		(solution or bath)) same (waste or disposal))	DERWENT	
	60	205/\$.ccls. and damascene and (electroless and	USPAT;	2003/05/01
		(electroplating or electroplated or electrolytically or	US-PGPUB;	08:48
		electrochemically))	EPO: JPO:	
		<i>'''</i>	DERWENT	
_	26	205/\$.ccls. and damascene and ((barrier or seed)	USPAT;	2003/05/01
		with electroless) and ((electroplating or	US-PGPUB;	08:49
		electroplated or electrolytically or electrochemically)	EPO; JPO;	
		with (seed or barrier))	DERWENT	
_	18	(204/\$.ccls. or 205/\$.ccls.) and (electroless near2	USPAT;	2003/05/01
		(solution or bath) with (waste or disposal or dispose))	US-PGPUB;	10:12
			EPO; JPO;	
			DERWENT	
-	522	(204/\$.ccls. or 205/\$.ccls.) and (zinc with (plating or	USPAT;	2003/05/01
		electroplating)) and ((alkali or "naoh" or "koh") with	US-PGPUB;	12:51
		((ammonium or tetramethylammonium) adj hydroxide)	EPO; JPO;	
		or alkaline)	DERWENT	
-	128	(204/\$.ccls. or 205/\$.ccls.) and (zinc with (plating or	USPAT;	2003/05/01
		electroplating)) and (((alkali or "naoh" or "koh") with	US-PGPUB;	12:52
		((ammonium or tetramethylammonium) adj hydroxide)	EPO; JPO;	
		or alkaline) with "ph")	DERWENT	
-	128	(204/\$.ccls. or 205/\$.ccls.) and (zinc with (plating or	USPAT;	2003/05/01
		electroplating)) and (((alkali! or "naoh" or "koh") with	US-PGPUB;	12:53
		((ammonium or tetramethylammonium) adj hydroxide)	EPO; JPO;	
		or alkaline) with "ph")	DERWENT	
-	35	(204/\$.ccls. or 205/\$.ccls.) and (zinc with (plating or	USPAT;	2003/05/01
		electroplating)) and (((alkali! or "naoh" or "koh") with	US-PGPUB;	12:53
	į l	(((ammonium or tetramethylammonium) adj	EPO; JPO;	
		hydroxide) or alkaline)) with "ph")	DERWENT	